

PCN # 2161

DATE: June 18, 2021

EXPECTED PCN SHIP DATE: June 18, 2021



Quality Assurance  
160 Rio Robles  
San Jose, CA 95134

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PROCESS CHANGE NOTICE  
 PRODUCT CHANGE NOTICE

MAXIM INTEGRATED HEREBY ISSUES NOTIFICATION OF CHANGE  
THAT MAY AFFECT THE FOLLOWING CATEGORIES:

DESIGN     WAFER FAB     ASSEMBLY     TEST     ELEC/MECH SPECS

AFFECTED PRODUCT:

Ordering P/N: (See PN listing XLS in PCN ZIP file)

CHANGE FROM: - For automotive products in TQFN/TDFN packages, body size 2x2mm to 7x7mm, Au wire size 0.8/1.0/1.3/2.0 mil  
Current mold compound Sumitomo G770HJ used at Assembler Vendor ASECL (ASE/CHUNG-LI/Taiwan).

CHANGE TO: -  
The replacement mold compound Sumitomo G700LA will be used for these devices at the same Assembly Vendor ASECL. This mold compound is an existing standard encapsulant for many other Maxim devices at this site.

JUSTIFICATION: Industry shortage of Sumitomo G770HJ requires that Maxim convert these devices to Sumitomo G700LA mold compound to ensure continuity of supply.

Maxim uses G700LA mold compound for many other automotive devices that are shipping in high volume since 2017.

- The AECQ-100 Qualification report is attached.
- Technical specification sheet G770HJ vs. G700LA is attached.
- Samples will be built upon request.
- There are no regulatory compliance changes to the material content of the devices.
- There are no changes to the form/fit/function of these devices using the new mold compound.

TRACEABILITY: Maxim Integrated maintains full traceability by device marking, packaging labels and shipment documents.

Maxim Integrated's Change Notification System is designed to keep our customer base apprised of major product, manufacturing, or facility improvements.

*Nasser Ali Chaouche*

Nasser AliChaouche / PCN Coordinator

For further information, please contact either of the people listed below.

Contact your local Maxim Integrated Company Representative    or    Nasser AliChaouche, PCN Coordinator  
408-601-5660 / pcn.coordinator@maximintegrated.com

# G700LA vs G770HJ

## EME-G770HJ

### TYPICAL PROPERTIES:

ITEM	TEST METHOD	UNIT	VALUES
SPIRAL FLOW	SB-U-03-003	Cm	160
GEL TIME (at 175°C)	SB-U-03-005	Sec	50
THERMAL EXPANSION $\infty 1$	SB-U-02-002	X 10 <sup>-5</sup> 1/°C	0.8
THERMAL EXPANSION $\infty 2$	SB-U-02-002	X 10 <sup>-5</sup> 1/°C	4.0
Tg	SB-U-02-002	°C	140
THERMAL CONDUCTIVITY	SB-U-02-004	W/m •°C	100x 10 <sup>-2</sup>
FLEXURAL STRENGTH	SB-U-01-001	N/ mm <sup>2</sup>	
(at 25°C)			160
(at 260°C)			22
FLEXURAL MODULUS	SB-U-01-002	X 10 <sup>2</sup> N/mm <sup>2</sup>	
(at 25°C)			270
(at 260°C)			7.0
SPECIFIC GRAVITY	SB-U-03-018	-----	2.02
VOLUME RESISTIVITY	SB-U-00-004	Ω - cm	1 x 10 <sup>11</sup>
(at 150°C)			
UL FLAME CLASS	SB-U-03-003	UL-94	V-0
WATER ABSORPTION	SB-U-03-002	% weight gain	0.15
(boiling, 24 h)			
EXTRACTED Na <sup>+</sup>	SB-U-04-043	ppm	1
EXTRACTED Cl <sup>-</sup>	SB-U-04-043	ppm	5

TYPICAL, NOT GUARANTEED PROPERTIES

### MOLDING AND POST MOLD CURE CONDITIONS:

	STANDARD	RANGE
TRANSFER PRESSURE	80 x10 <sup>5</sup> Pa	70-120 x10 <sup>5</sup> Pa
MOLD TEMPERATURE	180°C	175-185°C
CURE TIME (C or A)#	A/90 sec	70-120 sec
POST-MOLD CURE TEMP	175°C	170-180°C
POST-MOLD CURE TIME	6 h	4-8 h

## EME-G700LA Type L-A

### TYPICAL PROPERTIES:

ITEM	TEST METHOD	UNIT	VALUES
SPIRAL FLOW	SB-U-03-003	cm	135
GEL TIME (at 175°C)	SB-U-03-005	sec	50
THERMAL EXPANSION $\infty 1$	SB-U-02-002	X 10 <sup>-5</sup> 1/°C	1.0
THERMAL EXPANSION $\infty 2$	SB-U-02-002	X 10 <sup>-5</sup> 1/°C	3.9
Tg	SB-U-02-002	°C	125
THERMAL CONDUCTIVITY	SB-U-02-004	W/m •°C	96x 10 <sup>-2</sup>
FLEXURAL STRENGTH	SB-U-01-001	N/ mm <sup>2</sup>	
(at 25°C)			170
(at 260°C)			18
FLEXURAL MODULUS	SB-U-01-002	X 10 <sup>2</sup> N/mm <sup>2</sup>	
(at 25°C)			225
(at 260°C)			6.8
SPECIFIC GRAVITY	SB-U-03-018	-----	1.99
VOLUME RESISTIVITY	SB-U-00-004	Ω - cm	1 x 10 <sup>12</sup>
(at 150°C)			
UL FLAME CLASS	SB-U-03-003	UL-94	V-0
WATER ABSORPTION	SB-U-03-002	% weight gain	0.15
(boiling, 24 h)			
EXTRACTED Na <sup>+</sup>	SB-U-04-043	ppm	3
EXTRACTED Cl <sup>-</sup>	SB-U-04-043	Ppm	10

TYPICAL, NOT GUARANTEED PROPERTIES

### MOLDING AND POST MOLD CURE CONDITIONS:

	STANDARD	RANGE
TRANSFER PRESSURE	100 x10 <sup>5</sup> Pa	70-120 x10 <sup>5</sup> Pa
MOLD TEMPERATURE	180°C	165-185°C
CURE TIME (C or A)#	A/90 sec	60-120 sec
POST-MOLD CURE TEMP	175°C	170-180°C
POST-MOLD CURE TIME	6 h	4-8 h

**PURPOSE**

To qualify assembler ASE CHUNGLI to build 7x7 TQFN, 5X5 TQFN, 3X3 TDFN with side-wettable process.

**SUMMARY:**

All qualification lots assembled in ASE CHUNGLI have passed reliability qualification (Full Qualification Requirements/Acceptance Criteria). Therefore, assembler ASE CHUNGLI is conditionally qualified to build 3x3, 5x5 and 7x7 side wettable packages. These packages as tested (MSL-1) are not moisture sensitive and do not require bake-and-bag precautions for shipment and storage.

**Package Coverage**

Packages that can be covered by this qualification result in accordance with Maxim Qual By Extension (QBE) policy are all 3X3, 5X5, 7X7 side-wettable packages being assembled at ASE CHUNGLI with Au wire (G700LA + EN4900G).

**Package Material Information**

Description (Qual Type)	Maxim Std Qual
Operating Temperature	-40°C to +105°C / -40°C to +125°C
Temperature Grade	2 / 1
Fab Site	San Antonio 8 / MFN8
Fab Process	S45JST / BCD88
Die	AP12Z / AP35A-0C / MT06Y-4Z
Die Size (mils)	141X141 / 104X87
Assembly Location	ASE CHUNGLI
Package	T4877Y+11 / T2855Y+6 / T833Y+2
Wire Bond Material	1.3 mil Au / 2 mil Au / 1.0 mil Au
Die Coat	None
Mold Compound	G700LA
Die Attach	EN4900G
Lead Frame	Cu194
Lead Finish	100% Matte-Sn

## Qualification Requirements and Results

Rel#	R28341A		R28341B		R28341C
Lot#	TANX6A086A		TAKS1A053A		J984DA084MX
Device:	MAX16924GTM/VY+		MAX16984SATI/VY+		MAX6769TALD2/VY+
Die Type:	AP12Z		AP35A-0C		MT06Y-4Z
Die Size (mils)	206 X 206		128 X 128		70X94
Package Type (code):	T4877Y+11 / 48L 7x7 TQFN		T2855Y+6 / 28L 5x5 TQFN		T833Y+2 / TDFN 3X3
Date Code:	1542		1542		1527
Topmark:	DM		BV		AW
<b>Stress Test</b>	<b>Duration</b>	<b>Sampling Plan</b>	<b>Result</b>	<b>Result</b>	<b>Result</b>
Convection Reflow *2,3 260°C Peak	MSL 1, 3X	0/320	0/320	0/320	0/320
HAST *1,2,3 130°C / 85% R.H.	96 hrs.	0/77	0/77	0/77	0/77
Unbiased HAST *1,2 130°C / 85% R.H.	96 hrs.	0/77	0/77	0/77	0/77
Temperature Cycle *1,2,3 -65°C to 150°C	1000 cyc	0/77	0/77	0/77	0/77
High Temperature Storage *1,2,3 150°C	1000 hrs.	0/77	0/77	0/77	0/77
HTOL *2, 3, 4	1000 hrs.	0/77	0/77	0/77	0/77
Wire Bond Pull Minimum 5 grams-force	T(0)	0/200 wires	0/200wires	0/200wires	0/200wires
Physical Dimension	T(0)	0/15	0/15	0/15	0/15
Solderability (Pb-Free) 8 hrs steam ageing, 245C	T(0)	0/15	0/15	0/15	0/15
CSAM	T(0)	0/25	0/25	0/25	0/25
CSAM	MSL 1, 3X	0/25	0/25	0/25	0/25

Note:

- \*1. Convection reflow is used as preconditioning for SMD packages.
- \*2. Electrical tests pre- and post-stress were performed at +25°C.
- \*3. Electrical tests pre- and post-stress were performed at +105°C / +125C.
- \*4. Electrical tests pre- and post-stress were performed at -40°C.

Affected product numbers	PCN Proposed Ship Date
MAX16126TCA/V+T	18-Jun-21
MAX16838ATP/V+T	18-Jun-21
MAX16910CATA8/V+T	18-Jun-21
MAX16933CATIS/V+	18-Jun-21
MAX16977RATE/V+	18-Jun-21
MAX16984RATI/V+	18-Jun-21
MAX16984RATI/V+T	18-Jun-21
MAX16990ATCD/V+T	18-Jun-21
MAX2769BETI/V+	18-Jun-21
MAX9278AGTM/V+	18-Jun-21
MAX9278AGTM/V+T	18-Jun-21
MAX9288GTM/V+	18-Jun-21
MAX9288GTM/V+T	18-Jun-21
MAX96701GTG/V+	18-Jun-21
MAX96701GTG/V+T	18-Jun-21
MAX9736AETJ/V+	18-Jun-21
MAX9736AETJ/V+T	18-Jun-21
MAX98307ETE/V+T	18-Jun-21
MAX98357AGTE/V+	18-Jun-21
MAX98357AGTE/V+T	18-Jun-21